



Click [here](#) for the 3D model.

### Dimensions

|           |                  |
|-----------|------------------|
| Chip Size | 1210             |
| L         | 3.2mm +/-0.2mm   |
| W         | 2.5mm +/-0.2mm   |
| T         | 1.25mm +/-0.15mm |
| B         | 0.5mm +/-0.25mm  |

### Packaging Specifications

|                    |              |
|--------------------|--------------|
| Packaging          | Waffle, Tray |
| Packaging Quantity | 80           |

### General Information

|                  |   |
|------------------|---|
| Series           | SMD Indust COG HT200C   |
| Style            | SMD Chip  |
| Description      | SMD, MLCC, High Temperature, Ultra-Stable, Low Loss               |
| Features         | High Temp, Ultra-Stable, Low Loss                                 |
| RoHS             | Yes   |
| Termination      | Gold  |
| Marking          | No  |
| AEC-Q200         | No  |
| Component Weight | 40 mg   |
| Miscellaneous    | Moisture Sensitive Packaging. Gold (Au) 1.97 - 11.8 micro inches. |
| Shelf Life       | 26 Weeks  |
| MSL              | 1   |

### Specifications

|  |                        |
|--|------------------------|
| Capacitance  | 2200 pF                |
| Measurement Condition  | 1kHz 1.0Vrms           |
| Capacitance Tolerance  | 1%                     |
| Voltage DC   | 200 VDC                |
| Dielectric Withstanding Voltage                                    | 500 VDC                |
| Temperature Range  | -55/+200°C             |
| Temperature Coefficient  | COG                    |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1kHz 1.0Vrms |
| Dissipation Factor   | 0.1% 1kHz 1.0Vrms      |
| Aging Rate   | 0% Loss/Decade Hour    |
| Insulation Resistance  | 100 GOhms              |